



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-07-07
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

Uncertainty statement
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Legal statement			
Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32L071CBT3	ME5B*447XXXZ	A	0959	2025-07-07
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	187	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
2	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFP	7x7	48	Gull wing	
Comment	Package : 5B LQFP 48 7x7x1.4 1 0110596			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015			Response
1 - Product(s) meets EU RoHS requirement without any exemptions			true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)			false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)			false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions			false
Exemption Id.	Description		
,			

QueryList : REACH-21st January 2025				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	#N/A			

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ME5B*44TXXXZ		186.7186		6000000.0	1000000.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	9.574	mg	supplier	die	Silicon (Si)	7440-21-3		9.236	mg	964674	49465.18
				supplier	metallization	Aluminium (Al)	7429-90-5		0.025	mg	2627	134.70
				supplier	metallization	Copper (Cu)	7440-50-8		0.102	mg	10692	548.25
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.011	mg	1158	59.38
				supplier	metallization	Titanium (Ti)	7440-32-6		0.014	mg	1506	77.22
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	116	5.95
				supplier	Passivation	Silicon Nitride	12033-89-5		0.027	mg	2780	142.55
				supplier	Passivation	Silicon Oxide	7631-86-9		0.157	mg	16447	843.35
Leadframe (C7025)	M-011 Other inorganic materials	75.592	mg	supplier	alloy	Copper (Cu)	7440-50-8		72.936	mg	964855.2438	390618.80
				supplier	alloy	Nickel (Ni)	7440-02-0		2.097	mg	27745.86018	11232.83
				supplier	alloy	Silicium (Si)	7440-21-3		0.454	mg	6011.603039	2433.78
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.105	mg	1387.293009	561.64
Leadframe Coating (NiPdAu)	M-011 Other inorganic materials	0.406	mg	supplier	coating	Nickel (Ni)	7440-02-0		0.371	mg	914840	1987.15
				supplier	coating	Palladium (Pd)	7440-05-3		0.012	mg	29660	64.43
				supplier	coating	Gold (Au)	7440-57-5		0.011	mg	27750	60.28
				supplier	coating	Silver (Ag)	7440-22-4		0.011	mg	27750	60.28
Glue epoxy (EN4900)	M-011 Other inorganic materials	1.954	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		1.661	mg	850000	8895.81
				supplier	glue or soft solder	Acrylate	Proprietary		0.197	mg	101000	1057.03
				supplier	glue or soft solder	Additive	Proprietary		0.008	mg	4000	41.86
				supplier	glue or soft solder	Butadiene	Proprietary		0.020	mg	10000	104.66
				supplier	glue or soft solder	Organic Filler	Proprietary		0.018	mg	9000	94.19
				supplier	glue or soft solder	Polybutadiene	Proprietary		0.043	mg	22000	230.24
				supplier	glue or soft solder	peroxide cyclohexylidenebis	3006-86-8		0.008	mg	4000	41.86
				supplier	Bonding wire	Silver (Ag)	7440-22-4		0.519	mg	965000	2780.49
Bonding wire (Ag96.5)	M-011 Other inorganic materials	0.538	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.002	mg	3800	10.95
				supplier	Bonding wire	Palladium (Pd)	7440-05-3		0.016	mg	29200	84.14
				supplier	Bonding wire	Platinum (Pt)	7440-06-4		0.001	mg	2000	5.76
Encapsulation (EME_G700LS)	M-011 Other inorganic materials	98.654	mg	supplier	Moulding Compound	Solid Epoxy Resin	Proprietary		7.399	mg	75000	39626.79
				supplier	Moulding Compound	Phenol Resin	Proprietary		2.960	mg	30000	15850.72
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		80.354	mg	814500	430346.97
				supplier	Moulding Compound	Carbon-black	1333-86-4		0.543	mg	5500	2905.96
				supplier	Moulding Compound	Silicon oxide	7631-86-9		7.399	mg	75000	39626.79